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(54) TRANSFER MATERIAL AND ITS MANUFACTURING METHOD AS WELL AS WIRING BOARD MANUFACTURED BY USING THE SAME

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a transfer material capable of surely and easily transferring a fine

wiring pattern and a component pattern to a board.

SOLUTION: The transfer material comprises a first metal layer 101 as a carrier, a second metal layer 103 to be transferred to the board as the wiring pattern, and a release layer 102 for releasably laminating the first and second metal layers of at least three layers. A ruggedness corresponding to the wiring pattern is formed on a surface layer of the layer 101, and the layer 102 and the layer 103 are formed on the protruding region.

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